

In the Claims:

Claims 33-36 (Withdrawn)

Claim 37 (Currently Amended): A method of forming a plurality of wiring lines on conductive material on a board having a core layer to form a printed circuit board, comprising:

- (a) forming said plurality of wiring lines on a surface of said core layer, having first and second portions, the plurality of wiring lines formed on said surface of said core having side walls of a uniform thickness in height relative to said surface of said core layer; and
- (b) etching the first portion of a first of said plurality of wiring lines, such that the first portion has a planar surface completely across said first portion, joining said side walls, and is thinner in height relative to said surface of said core layer than the second portion, such that cross-talk noise between adjacent two wiring lines is reduced, wherein the first portion is parallel to at least one of the plurality of wiring lines other than the first of the plurality of wiring lines.

Claim 38 (Currently Amended): The method as claimed in claim 37, wherein a second of said plurality of said wiring lines is provided, spaced from said first wiring line of said plurality of wiring lines having said first and second portions, said second wiring line having third and fourth portions, and etching said second wiring line such that the third portion is thinner in height relative to said surface of said core layer than the fourth portion, wherein the third portion is parallel to the first portion.